

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior version, and listings, of claims in the application:

Listing of Claims:

1-7. (Canceled)

8. (Currently Amended) A device for detecting a radiation signal, comprising:

- a first detector;
- a second detector;
- a first chip on which are arranged the first detector and the second detector;
- a first filter;
- a second filter; and
- a second chip on which are arranged the first filter and the second filter; wherein:
 - the first chip and the second chip are connected to one another in a hermetically sealed fashion.

9. (Previously Presented) The device as recited in Claim 8, wherein:

- the first chip and the second chip are connected by a wafer-bonding.

10. (Previously Presented) The device as recited in Claim 8, wherein:

- each of the first detector and the second detector includes one of a thermopile, a temperature-sensitive resistor, and a temperature-sensitive diode.

11. (Previously Presented) The device as recited in Claim 8, further comprising:

- an absorber layer provided on at least one of the first detector and the second detector.

12. (Previously Presented) The device as recited in Claim 8, wherein:

- the first chip includes a first substrate, and
- the first detector and the second detector are thermally decoupled from the first substrate.

13. (Previously Presented) The device as recited in Claim 8, wherein:

- at least one of the first filter and the second filter includes a Fabry-Perot filter.

14. (Previously Presented) The device as recited in Claim 8, further comprising:

- at least one further detector; and
- at least one further filter.

15. (Currently Amended) A device for measuring a concentration of a substance in a beam path of a radiation source, comprising:

- a first detector;

a second detector;
a first chip on which are arranged the first detector and the second detector;
a first filter;
a second filter; and
a second chip on which are arranged the first filter and the second filter; wherein:
the first chip and the second chip are connected to one another in a hermetically sealed fashion.

16. (New) The device as recited in claim 15, wherein a hermetic seal between the first and second chips includes a bonding web.

17. (New) The device as recited in claim 15, wherein the first detector and the second detector are hermetically isolated from each other.

18. (New) The device as recited in claim 8, wherein a hermetic seal between the first and second chips includes a bonding web.

19. (New) The device as recited in claim 8, wherein the first detector and the second detector are hermetically isolated from each other.